



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.

REVISION HISTORY			
ECO	REV	DESCRIPTION	APPR
	2	PRODUCTION	TOM G.
			DATE
			11-30-12

APPROVALS

PCB DES.	HZ
APP ENG.	TOM G.
TITLE: TOP ASSEMBLY DRAWING	
17V VIN SYNCHRONOUS STEP-DOWN REGULATOR WITH ULTRA-LOW QUIESCENT CURRENT	
SIZE	IC NO. LTC3621EDCB-2
N/A	REV. 2
DEMO CIRCUIT 1864A	
FILENAME: DC1864A-2.PCB	
SHT 1 OF 1	

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